

## REMARKS

In view of the above amendments and following remarks, reconsideration and further examination are requested.

In response to the Examiner's indication that Figure 15 should be designated by a legend such as --Prior Art--, provided herewith is a replacement formal drawing for Figure 15 which labels this figure as --Prior Art--.

In response to the Examiner's requirement of a new title, the following new title is hereby provided, --PROCESSING APPARATUS TO BE SEALED AGAINST WORKPIECE--.

The specification and abstract have been reviewed and revised to make editorial changes thereto and generally improve the form thereof, and a substitute specification and abstract are provided. No new matter has been added by the substitute specification and abstract.

The instant invention pertains to a processing apparatus for processing a workpiece. Processing apparatus for processing workpieces are known in the art; however, these apparatus suffer from a drawback in that they are larger than the workpieces to be processed thereby. This is especially true during current times because workpieces such as semiconductor wafers and liquid crystal panels, for example, are continually being increased in size, whereby apparatus used to process these workpieces are also increasing in size. This increase in size of the apparatus results in a larger installation space being required for the apparatus, and also lends itself to non-efficient use of processing material such as a process gas or a cleaning liquid. Accordingly, there exists a need for reducing installation space required for these processing apparatus, and also a need for enabling more efficient use of processing materials.

Applicants have addressed these needs by developing a processing apparatus that is smaller in cross-sectional area than a surface of a workpiece to be processed by the apparatus. Specifically, with regard to Figures 1 and 2, for example, the processing apparatus comprises a cover 2 and a sealing portion 4 at a lower end of the cover. The cover 2 is smaller in cross-sectional area than a surface 11 of a workpiece 10 to be processed, and accordingly, when the cover is placed onto the surface 11 the sealing portion 4 cooperates with the surface 11 such that the cover and the surface of the workpiece form a process chamber 3. Claim 1 is believed to be representative of Applicants' inventive processing apparatus.

Claims 1 and 2 were rejected under 35 U.S.C. § 102(b) as being anticipated by Davison et al. And, claims 3-10 were objected to as being dependent upon a rejected base claim, but were indicated to be allowable if rewritten in independent form including all of the limitations of the base claim and any intervening claims. The indication of allowable subject matter is greatly appreciated, and accordingly, claims 3, 4, 5, 6, 7, 9 and 10 have been rewritten in independent form, while also being slightly modified so as to improve their form without departing from the intended scope thereof. Thus, claims 3-10 are believed to be allowable. Also, claim 1 has been amended so as to further distinguish this claim from Davison et al.

In this regard, claim 1 now recites

A processing apparatus for processing a workpiece,  
comprising:  
    a cover for covering a portion of a surface, to be  
processed, of the workpiece;  
    a process chamber to be formed by said cover and  
the surface, to be processed, of the workpiece; and  
    **a sealing portion** at a lower end of said cover for  
sealing said process chamber when formed, said sealing  
portion to be provided between said cover and the surface of  
the workpiece so as **to face the surface of the workpiece**. (emphasis added)

Thus, as now required by claim 1, the sealing portion at the lower end of the cover is to face the surface of the workpiece. Such a feature is not taught or suggested in Davison et al.

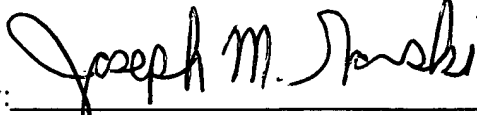
That is, while a sealing portion, 20, 21 and 22, is provided in the apparatus of Davison et al., this sealing portion is positioned outwardly of workpiece 14, and thus is not designed to face the surface of the workpiece, as is now required by claim 1. Accordingly, the process chamber 4 of Davison et al. is not formed by reference member 2 and a surface of the substrate 14, but is rather formed by reference member 2 and stage member 3. Thus, claim 1 is not anticipated by Davison et al., whereby claims 1 and 2 are allowable over Davison et al.

In view of the above amendments and remarks, it is respectfully submitted that the present application is in condition for allowance and an early Notice of Allowance is earnestly solicited.

If after reviewing this Amendment, the Examiner believes that any issues remain which must be resolved before the application can be passed to issue, the Examiner is invited to contact the Applicants' undersigned representative by telephone to resolve such issues.

Respectfully submitted,

Nobuharu NOJI et al.

By: 

Joseph M. Gorski  
Registration No. 46,500  
Attorney for Applicants

JMG/edg  
Washington, D.C. 20006-1021  
Telephone (202) 721-8200  
Facsimile (202) 721-8250  
September 23, 2004

**AMENDMENTS TO THE DRAWINGS:**

***A Replacement Formal Drawing for Figure 15 has been filed concurrently.***